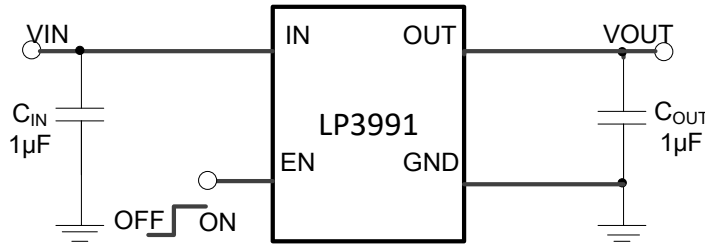
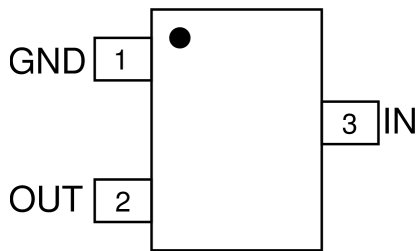




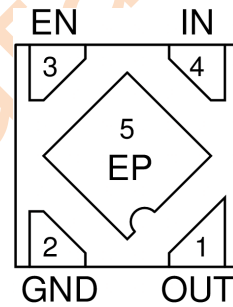
Application Diagram



Pin Configuration



SOT23 (Top View)



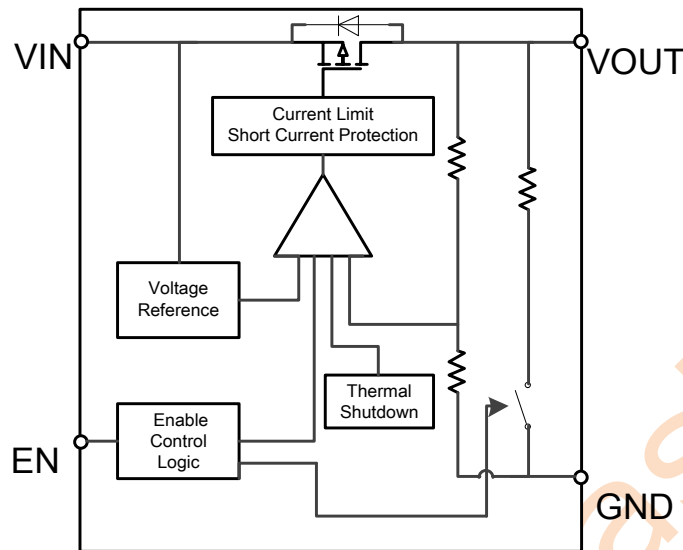
TDFN-4 (Bottom View)

Pin Description

Pin No. SOT23	Name	Description
1	GND	Ground.
2	OUT	Regulated output. A minimum 0.1µF ceramic capacitor is needed from the pin to ground.
3	IN	Input and power source. A small capacitor is recommended from the pin to ground.
Pin No. TDFN-4		
1	OUT	Regulated output. A minimum 0.1µF ceramic capacitor is needed from the pin to ground.
2	GND	Ground.
3	EN	Active-high enable pin. 1: enable the device. 0 or floating: disable the device.
4	IN	Input and power source. A small capacitor is recommended from this pin to ground.
5	EP	Exposed Pad for thermal dissipation. Need to be tied to ground.



Functional Block Diagram



Absolute Maximum Ratings (Note 1)

- IN to GND ----- -0.3V to 6.5V
- OUT to GND ----- -0.3V to ($V_{IN} + 0.3V$) or 6.5V
- EN to GND ----- -0.3V to 6.5V
- Output Current ----- 300mA
- Maximum Junction Temperature (T_J) ----- 150°C
- Maximum Soldering Temperature (At leads, 10 sec) ----- 260°C

*Note 1: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Thermal Information

- Maximum Power Dissipation (SOT23, P_D , $T_A \leq 25^\circ\text{C}$) ----- 420mW
- Thermal Resistance (SOT23, θ_{JA}) (Note 2) ----- 240 °C/W
- Maximum Power Dissipation (TDFN-4, P_D , $T_A \leq 25^\circ\text{C}$) ----- 390mW
- Thermal Resistance (TDFN-4, θ_{JA}) (Note 2) ----- 256 °C/W

*Note 2: Measured using 2S2P JEDEC standard PCB with ambient temperature < 25°C

Electro-Static Discharge and Latch-up

- HBM (Human Body Model, JEDEC JS-001) ----- 2000V
- CDM (Charged Device Model, JEDEC JS-002) ----- 500V



Recommended Operating Conditions

- Input and supply voltage on IN ----- 1.5V to 5.5V
- Output DC current ----- Up to 250mA
- Output capacitor ----- $\geq 0.1\mu\text{F}$
- Operating ambient temperature ----- -40°C to 85°C

Electrical Characteristics

The parameters are specified under conditions: V_{IN} is equal to the greater value between $V_{\text{OUT(NOM)}} + 0.5\text{V}$ and 2.0V , $-40^{\circ}\text{C} \leq T_{\text{J}} \leq 85^{\circ}\text{C}$, $I_{\text{OUT}} = 1\text{mA}$, $C_{\text{IN}} = C_{\text{OUT}} = 1\mu\text{F}$, unless otherwise noted. Typical values are at $T_{\text{J}} = 25^{\circ}\text{C}$.

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
Output voltage accuracy		$T_{\text{J}} = 25^{\circ}\text{C}$	-1.5		1.5	%
Output voltage accuracy over temperature		$-40^{\circ}\text{C} \leq T_{\text{J}} \leq 85^{\circ}\text{C}$	-3		3	%
Input quiescent current	I_{Q}	$V_{\text{IN}} = 1.5\text{V to } 5.5\text{V}$, $V_{\text{EN}} = V_{\text{IN}}$, no load		5		μA
Input shutdown current	I_{SHDN}	$V_{\text{IN}} = 1.5\text{V to } 5.5\text{V}$, $V_{\text{EN}} = 0\text{V}$, no load		0.1		μA
Line regulation	$\frac{\Delta V_{\text{OUT}}}{\Delta V_{\text{IN}} \times V_{\text{OUT}}}$	$I_{\text{OUT}} = 20\text{mA}$, $V_{\text{IN}} = (V_{\text{OUT(NOM)}} + 1\text{V})$ to 6V		0.02	0.05	%/V
Load regulation	ΔV_{LOAD}	$I_{\text{OUT}} = 1\text{mA to } 100\text{mA}$, $V_{\text{IN}} = V_{\text{OUT(NOM)}} + 1.5\text{V}$, $-40^{\circ}\text{C} \leq T_{\text{J}} \leq 85^{\circ}\text{C}$		15	40	mV
Dropout voltage ⁽³⁾	V_{DROP}	$I_{\text{OUT}} = 100\text{mA}$, $T_{\text{A}} = 25^{\circ}\text{C}$		0.17	0.33	V
Output current limit	I_{LIM}	$V_{\text{IN}} = V_{\text{OUT(NOM)}} + 1.0\text{V}$, $V_{\text{OUT}} = 0.9 \times V_{\text{OUT(NOM)}}$		300		mA
Short circuit protection	I_{SHORT}	$V_{\text{IN}} = V_{\text{OUT(NOM)}} + 1.0\text{V}$, $V_{\text{OUT}} = 0\text{V}$		50		mA
Output voltage noise	V_{NOISE}	$\text{BW} = 10\text{Hz to } 100\text{kHz}$, $I_{\text{OUT}} = 30\text{mA}$		230		μV_{RMS}
Power supply rejection ratio	PSRR	$V_{\text{IN}} = V_{\text{OUT(NOM)}} + 1.5\text{V}$, $I_{\text{OUT}} = 30\text{mA}$, $f = 1\text{kHz}$, $\Delta V_{\text{RIPPLE}} = 0.2 \times V_{\text{PP}}$		46		dB
EN logic high voltage level	V_{IH}		1.2			V
EN logic low voltage level	V_{IL}				0.3	V
EN pin leakage current	I_{EN}			30		nA
Output discharge resistance	R_{DIS}	$V_{\text{EN}} = 0\text{V}$		1		k Ω

*Note 3: Dropout voltage is measured under condition $V_{\text{IN}} = V_{\text{OUT(NOM)}} - 0.1\text{V}$.



Detailed Description

Overview

The LP3991 is a Low dropout voltage regulator with ultra-low current consumption. It has fixed output voltage with good transient performance. The product is available in ultra-small package 1mm x 1mm TDFN-4.

Selectable output voltage

The product will output fixed voltage 3.3V as long as the input voltage is higher than $V_{OUT(NOM)} + V_{DROP}$. The device can source up to 250mA loading current.

Enable function

The EN pin is an active high logic input pin which is compatible with 1.2V control logic. The internal power element is turned off when EN pin is pulled low.

When the EN pin is pulled high, the LP3991 will be activated and output voltage according to setting.

Auto discharge

The LP3991 integrated a quick discharge function. When the device is disabled by pulling down EN pin, a resistor between OUT and GND will discharge the output capacitor energy. The resistance is 1k Ω (typical).

Over current protection

The device features a current limit function when the over current event is detected to reach 300mA (typical) and output voltage will drop accordingly. On the heavy load condition, the current limit value will be reduced along with output voltage drops. If the output is shorted to ground, the current limit value will foldback to 50mA(typical), as showed in the *Electrical Characteristics Table*.

Application Information

Capacitor consideration

External capacitors on IN and OUT are recommended in application, 0.1 μ F for C_{OUT} and 1 μ F for C_{IN} at least. Closer placement of the capacitors to the device, both IN and OUT, would be better for stability.

Power Dissipation

The internal power dissipation from the power MOSFET, when it is turned on, is the main source of junction temperature rising. In this case, the power dissipation and the junction temperature in conducting mode can be calculated as following:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT}$$

P_D : Power Dissipation (W)

V_{IN} : Input voltage (V)

V_{OUT} : Output voltage (V)

I_{OUT} : Output current (A)

$$T_J = P_D \times \theta_{JA} + T_A$$

T_J : Junction temperature ($^{\circ}$ C)

θ_{JA} : Package thermal resistance ($^{\circ}$ C /W) (Note 4)

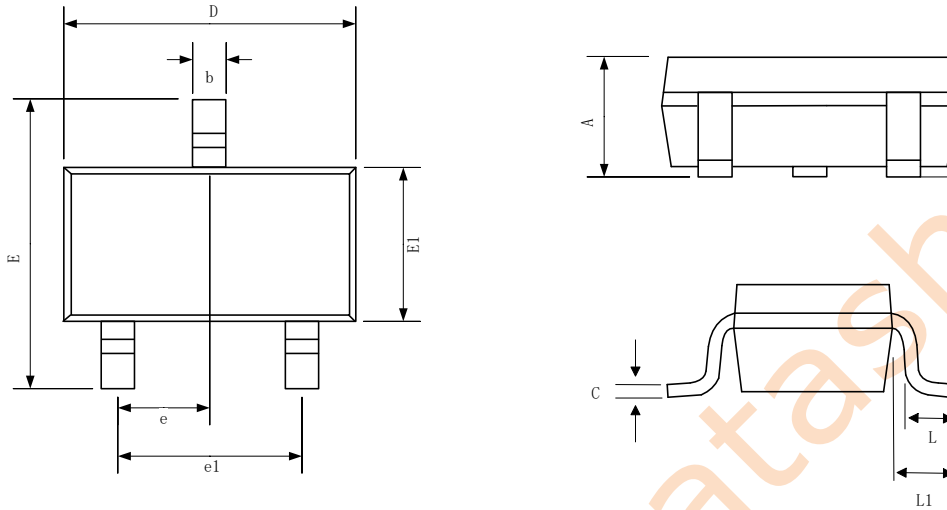
T_A : Ambient temperature ($^{\circ}$ C)

***Note 4:** The calculation base on thermal resistance is only valid in Lab condition. The value of θ_{JA} could change in customer PCB environment.



Package Information

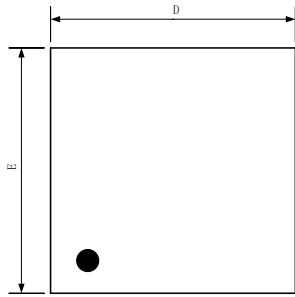
SOT23



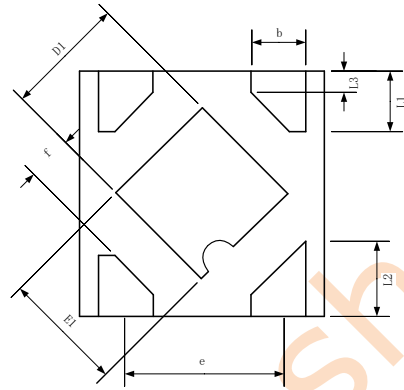
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	MIN	NOM	MAX
A	0.900		1.200
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.008	0.120	0.150
D	2.800	2.900	3.000
E	2.250	2.400	2.550
E1	1.200	1.300	1.400
e	0.950BSC		
e1	1.900BSC		
L	0.200	0.350	0.500
L1	0.550REF		



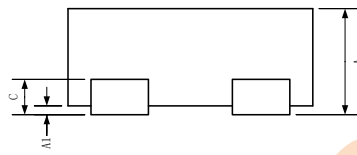
TDFN-4



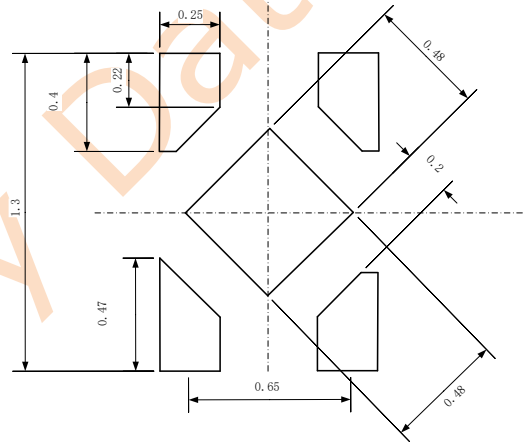
TOP VIEW



BOTTOM VIEW



SIDE VIEW



Recommended Land Pattern

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.35	-	0.40
A1	0.00	0.02	0.05
b	0.20	0.25	0.30
c	0.07	0.12	0.17
D	0.95	1.00	1.05
D1	0.43	0.48	0.55
E	0.95	1.00	1.05
E1	0.43	0.48	0.55
e	0.65BSC		
L1	0.2	0.25	0.30
L2	0.27	0.32	0.37
L3	0.09REF		
f	0.18REF		